

Polar™ Power MOSFET HiPerFET™

IXFK140N30P IXFX140N30P

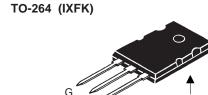
N-Channel Enhancement Mode Avalanche Rated Fast Intrisic Diode

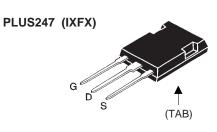


Symbol	Test Conditions	Maximum F	Ratings
V _{DSS}	$T_{_{\rm J}}$ = 25°C to 150°C	300	V
V _{DGR}	$T_J = 25^{\circ}C$ to 150°C, $R_{GS} = 1M\Omega$	300	V
V _{GSS}	Continuous	±20	V
V _{GSM}	Transient	±30	V
I _{D25}	T _c = 25°C	140	A
LRMS	Lead Current Limit, RMS	75	Α
I _{DM}	$T_{\rm C} = 25^{\circ}$ C, pulse width limited by $T_{\rm JM}$	300	Α
I _A	T _C = 25°C	70	A
E _{as}	$T_{c} = 25^{\circ}C$	5	J
dV/dt	$I_{_{\mathrm{S}}} \le I_{_{\mathrm{DM}}}, V_{_{\mathrm{DD}}} \le V_{_{\mathrm{DSS}}}, T_{_{\mathrm{J}}} \le 150^{\circ}\mathrm{C}$	20	V/ns
P _D	T _c = 25°C	1040	W
T _J		-55 +150	°C
T _{JM}		150	°C
T _{stg}		-55 +150	°C
T,	1.6mm (0.062 in.) from case for 10s	300	°C
T _{SOLD}	Plastic body for 10s	260	°C
M _d	Mounting force (PLUS247) Mounting torque (TO-264)	20120/4.527 1.13/10	N/lb. Nm/lb.in.
Weight	PLUS247 TO-264	6 10	g g

			cteristic Values Typ. Max.		
BV _{DSS}	$V_{GS} = 0V, I_D = 3mA$	300			V
V _{GS(th)}	$V_{DS} = V_{GS}, I_{D} = 8mA$	3.0		5.0	V
I _{GSS}	$V_{GS} = \pm 20V, V_{DS} = 0V$			±200	nA
I _{DSS}	$V_{DS} = V_{DSS}$ $V_{GS} = 0V$ $T_{J} = 125^{\circ}C$			I	μA mA
R _{DS(on)}	V _{GS} = 10V, I _D = 0.5 • I _{D25} , Note 1		20	24	mΩ

300V V_{DSS} 140A D25 ≤ $24m\Omega$ $\mathbf{R}_{\mathrm{DS(on)}}$ 200ns \leq





(TAB)

G = Gate= Drain S = SourceTAB = Drain

Features

- Fast intrinsic diode
- Avalanche Rated
- Low R_{DS(ON)} and Q_G
 Low package inductance

Advantages

- Easy to mount
- Space savings
- High power density

Applications

- DC-DC coverters
- · Battery chargers
- Switched-mode and resonant-mode power supplies
- DC choppers
- · AC and DC motor control
- Uninterrupted power supplies
- High speed power switching applications



Symbol	•			racteristic Values	
$(T_J = 25^{\circ}C, \iota$	unless otherwise specified)	Min.	Тур.	Max.	
\mathbf{g}_{fs}	$V_{DS} = 20V, I_{D} = 0.5 \bullet I_{D25}, Note 1$	50	90	S	
C _{iss}			14.8	nF	
C _{oss}	$V_{GS} = 0V, V_{DS} = 25V, f = 1MHz$		1830	pF	
C _{rss}			55	pF	
t _{d(on)}	Resistive Switching Times		30	ns	
t _r	$V_{GS} = 10V, V_{DS} = 0.5 \cdot V_{DSS}, I_{D} = 0.5 \cdot I_{D25}$ $R_{G} = 1\Omega \text{ (External)}$		30	ns	
t _{d(off)}			100	ns	
t _f			20	ns	
$Q_{g(on)}$			185	nC	
Q _{gs}	$V_{GS} = 10V, V_{DS} = 0.5 \cdot V_{DSS}, I_{D} = 0.5 \cdot I_{D25}$		72	nC	
Q_{gd}			60	nC	
R _{thJC}				0.12 °C/W	
R _{thCS}			0.15	°C/W	

Source-Drain Diode

SymbolTest ConditionsChar $(T_J = 25^{\circ}C, \text{ unless otherwise specified})$ Min.		_	racteristic Values Typ. Max.	
I _s	$V_{GS} = 0V$		140	Α
I _{sm}	Repetitive, pulse width limited by $T_{_{\rm JM}}$		560	Α
V _{SD}	$I_F = 70A, V_{GS} = 0V, \text{ Note 1}$		1.3	V
t _{rr} Q _{RM} }	$I_{_{\rm F}} = 25 {\rm A}, -{\rm di}/{\rm dt} = 100 {\rm A}/\mu {\rm s}$ $V_{_{\rm R}} = 100 {\rm V}, V_{_{\rm GS}} = 0 {\rm V}$	0.6 6.0	200	nS μC A

Note 1: Pulse test, $t \le 300\mu s$; duty cycle, $d \le 2\%$.

TO-264 (IXFK) Outline | To-264 (IXFK) Outline | To-264 |

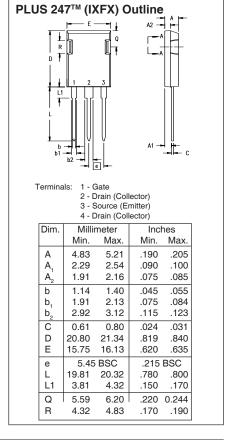


Fig. 1. Output Characteristics @ 25°C

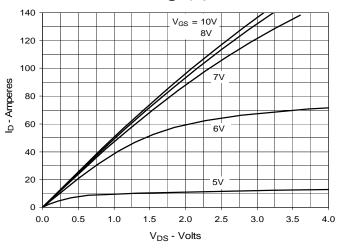


Fig. 3. Output Characteristics @ 125°C

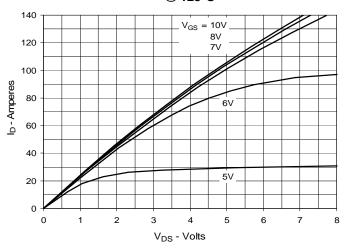


Fig. 5. R_{DS(on)} Normalized to I_D = 70A Value vs. Drain Current

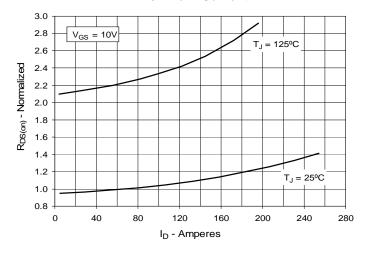


Fig. 2. Extended Output Characteristics @ 25°C

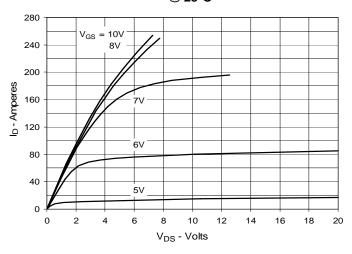


Fig. 4. R_{DS(on)} Normalized to I_D = 70A Value vs. Junction Temperature

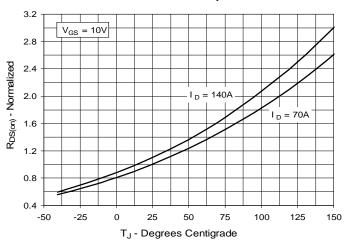


Fig. 6. Maximum Drain Current vs.

Case Temperature

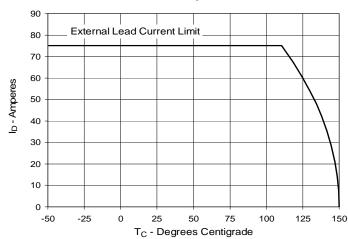


Fig. 7. Input Admittance

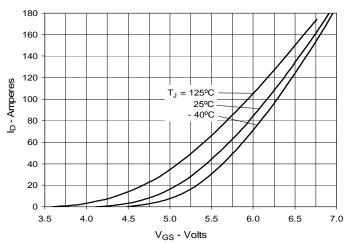


Fig. 8. Transconductance

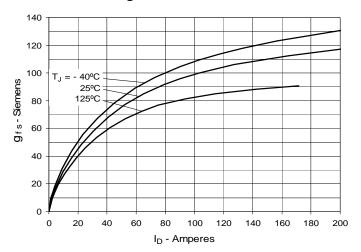


Fig. 9. Forward Voltage Drop of Intrinsic Diode

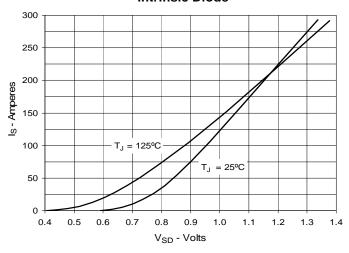


Fig. 10. Gate Charge

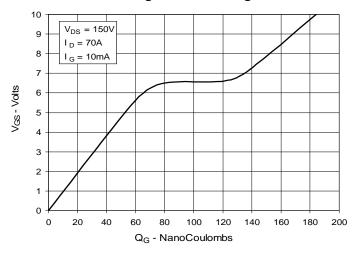


Fig. 11. Capacitance

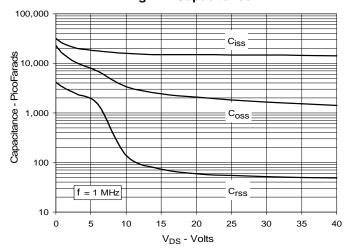
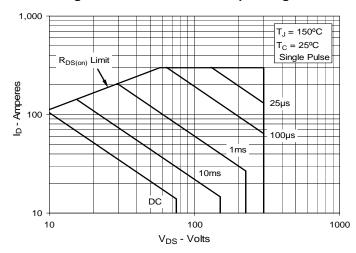


Fig. 12. Forward-Bias Safe Operating Area



IXYS reserves the right to change limits, test conditions, and dimensions.

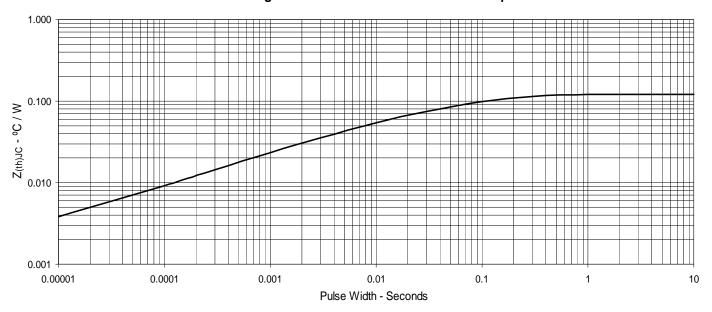


Fig. 13. Maximum Transient Thermal Impedance

